

November 04, 2025

BSE Ltd

Corporate Relationship Dept.,
14th floor, P. J. Tower,
Dalal Street, Fort
Mumbai - 400 001

National Stock Exchange of India Ltd

Exchange Plaza, Plot no. C/1, G Block,
Bandra-Kurla Complex,
Bandra (E),
Mumbai - 400 051

Scrip Code – 543664

Scrip Symbol – KAYNES

Dear Sir/Madam,

Subject: Investors/ Earnings Presentation under Regulation 30 of SEBI (Listing Obligations and Disclosure Requirements) Regulations, 2015.

With reference to Regulation 30 of the SEBI (Listing Obligations and Disclosure Requirements) Regulations, 2015, please find enclosed the Investors/ Earnings Presentation for the Quarter and Half year ended September 30, 2025. The Company will use this presentation for any meeting scheduled with analysts or institutional investors up to December 31, 2025.

The above information will also be available on the website of the Company at www.kaynestechnology.co.in.

Request to kindly take this intimation on record.

Thanking You,
Yours faithfully,
For **Kaynes Technology India Limited**

Anuj Mehtha

Company Secretary and Compliance Officer
ICSI Membership No: FCS 13802

Enclosed: As above

KAYNES TECHNOLOGY INDIA LIMITED

CIN: L29128KA2008PLC045825

Website: www.kaynestechnology.co.in Email ID: kaynestechnology@kaynestechnology.net

H.O & Regd Office: 23-25, Belagola, Food Industrial Estate Metagalli PO, Mysore 570016, Karnataka, India

Telephone No: +91 8212582595



Kaynes Technology India Limited

Investor Presentation | November 2025

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Financial Highlights

H1 FY26 Results Snapshot (Consolidated)



₹ 80,994 mn

Order Book

₹ 54,228 mn as of Sep-24



₹ 15,797 mn

Revenue

47% YoY



₹ 2,610 mn

EBITDA

75% YoY



16.5%

EBITDA Margin

270 bps YoY



₹ 1,960 mn

Profit After Tax

77% YoY



12.4 %

PAT Margin

210 bps YoY



₹ 46,786 mn

Networth

₹ 25,968 mn as of Sep-24



₹ 4,218 mn

Net Debt

₹ 4,997 mn as of Sep-24



16.7%

ROCE

18.6% in Sep-24



14.2%

ROE

17.6% in Sep-24



116 Days

**Net working capital
days**

108 days in Sep-24



0.1

Net Debt to Equity

0.2 as of Sep-24

ROCE, ROE and Net debt are adjusted for unutilized IPO & QIP proceeds.

Q2 FY26 Results Snapshot (Consolidated)



₹ 9,062 mn

Revenue
58% YoY



₹ 1,480 mn

EBITDA
80% YoY



16.3%

EBITDA Margin
190 bps YoY



₹1,214 mn

Profit After Tax
102% YoY



13.4%

PAT Margin
290 bps YoY



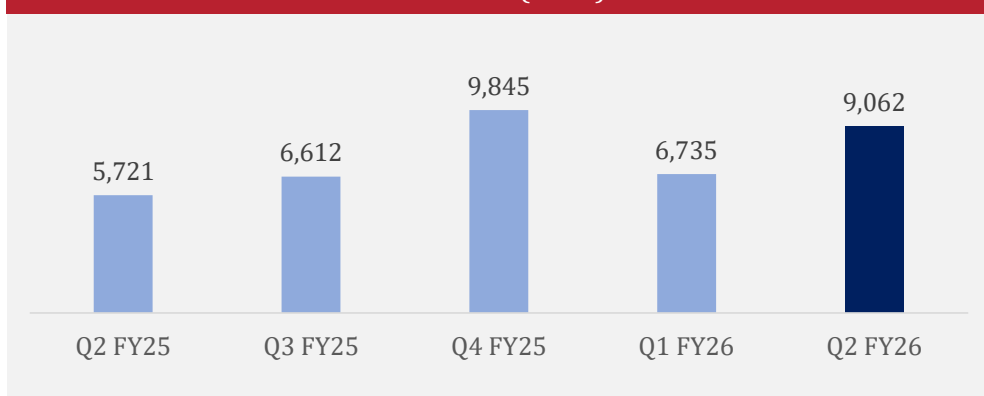
228

Finance Cost
3% YoY

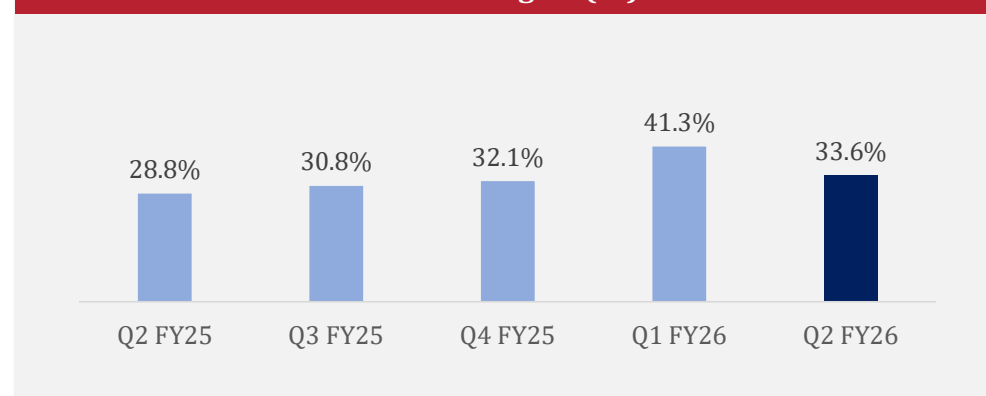
ROCE, ROE and Net debt are adjusted for unutilized IPO & QIP proceeds.

Consistent quarterly financial performance – Q2 FY26

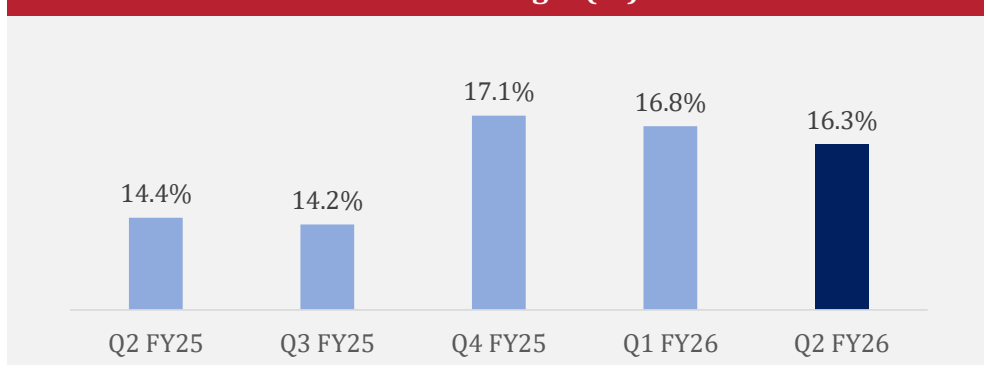
Revenue (₹ Mn)



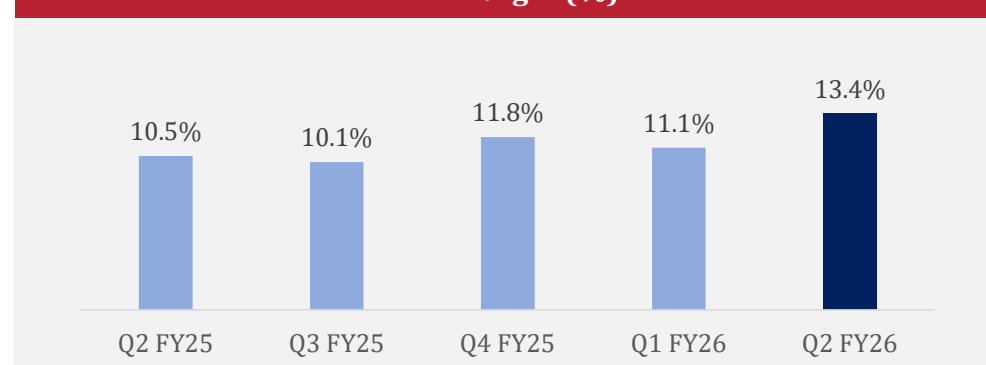
Gross Margins (%)



EBITDA Margin (%)



PAT Margin (%)



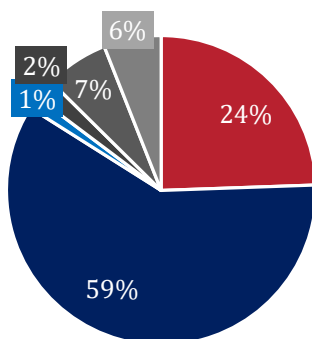
Diversified Revenue Mix



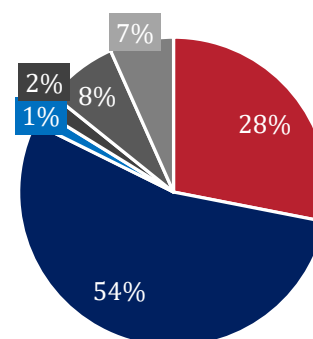
H1 FY26

Revenue across verticals

H1 FY25



- Automotive
- Industrial incl EV
- Aerospace, Outer-space & Strategic Electronics
- Medical
- Railways
- IoT / IT, Cons and Others

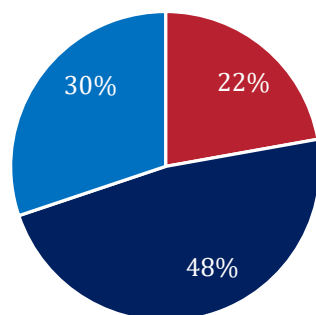


- Automotive
- Industrial incl EV
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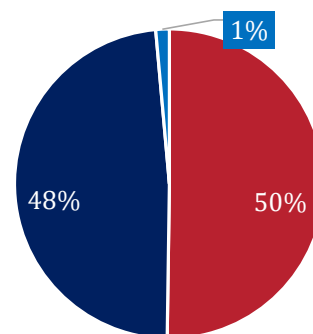
H1 FY26

Revenue across Segments

H1 FY25



- OEM - Turnkey - Box Build
- OEM - Turnkey - PCBA
- ODM & Prod. Eng. and IoT solutions

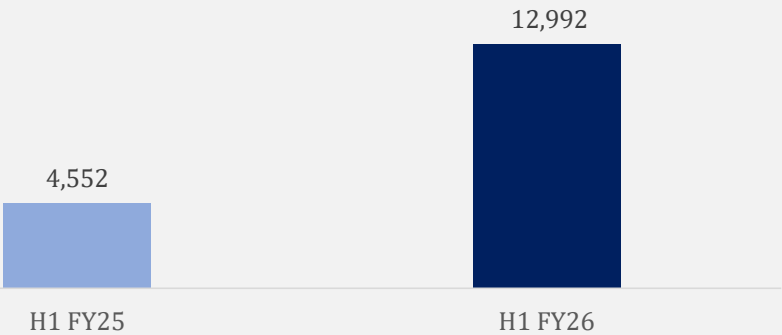


- OEM - Turnkey - Box Build
- OEM - Turnkey - PCBA
- ODM & Prod. Eng. and IoT solutions

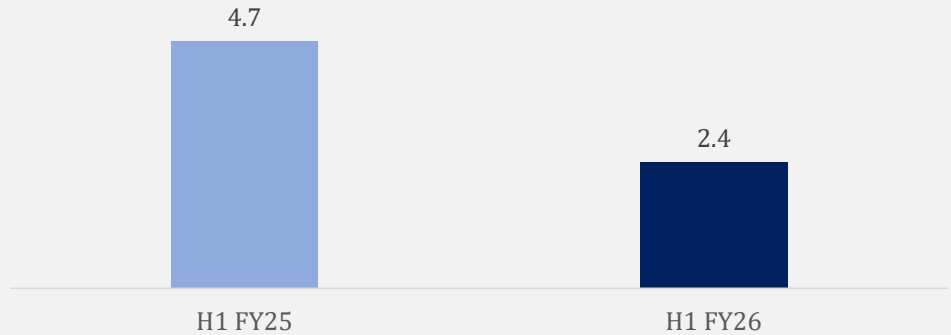
Half-yearly financial performance



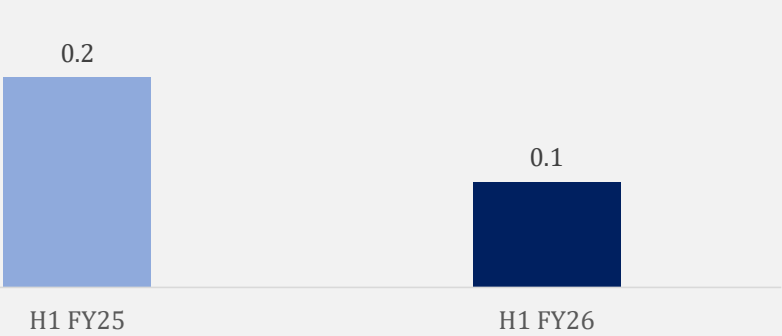
Gross Block (₹ Mn)



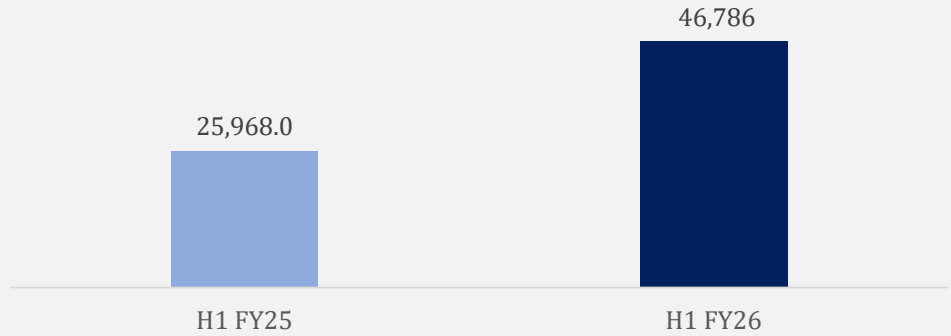
Asset Turnover ratio (x)



Net Debt/Equity (x)



Networth (₹ Mn)

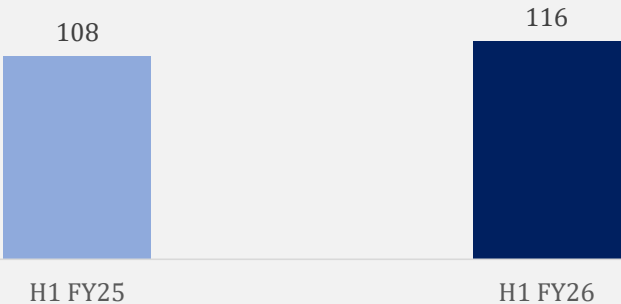


Note: Asset Turnover Ratio is annualized

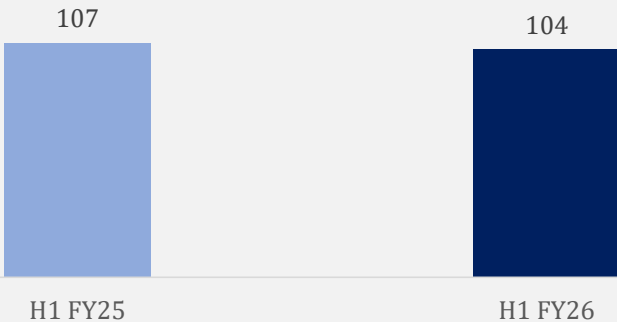
Half-yearly financial performance



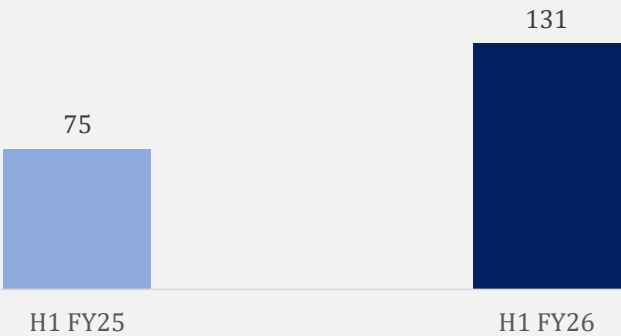
Net Working Capital Days



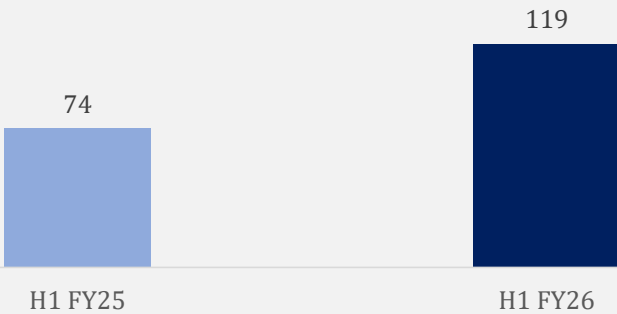
Inventory Days



Receivable Days



Payable Days



Q2 FY26 and H1 FY26 - Profit & Loss Statement (Consolidated)



Particulars (₹ Mn)	Q2 FY25	Q2 FY26	YoY	H1 FY25	H1 FY26	YoY
Revenue from operations	5,721	9,062	58%	10,761	15,797	47%
Raw material cost	4,073	6,013	48%	7,737	9,969	29%
Employee expenses	399	773	94%	734	1,362	85%
Other expenses	428	797	86%	799	1,856	132%
EBITDA	821	1,480	80%	1,490	2,610	75%
EBITDA margin (%)	14.4%	16.3%	190 BPS	13.8%	16.5%	270 BPS
Depreciation and amortization expense	86	166	93%	170	323	90%
Other income	336	431	28%	619	702	13%
Finance cost	221	228	3%	449	512	14%
Profit before tax	849	1,517	79%	1,491	2,478	66%
Total tax expenses	247	303	23%	381	517	36%
Net profit after tax	602	1,214	102%	1,110	1,960	77%
Net profit margin (%)	10.5%	13.4%	290 BPS	10.3%	12.4%	210 BPS

Balance Sheet as of H1 FY26 (Consolidated)



Particulars (₹ Mn)	Sep FY25	Sep FY26
Gross Block (tangible assets - including CWIP)	5,730	12,417
Accumulated Depreciation	786	2,098
Net Block (tangible assets)	4,944	10,319
Intangible assets (net block – including intangible assets work in-progress)	984	8,504
Other non-current assets	5,008	13,163
Total non-current assets	10,936	31,986
Inventories	7,129	9,823
Trade receivables	5,307	11,223
Cash and cash equivalents	12,123	10,527
Other current assets	2,467	3,774
Total current assets	27,026	35,347
Total Assets	37,962	67,333
Borrowings	433	3,099
Other non-current liabilities	323	491
Total non-current liabilities	756	3,590
Short-term borrowings	6,395	5,379
Trade payables	4,059	8,371
Other current liabilities	741	3,147
Total Current Liabilities	11,195	16,897
Total Equity & Reserves	26,010	46,847
Total Equity and Liabilities	37,962	67,333

H1 FY26 - Cash Flow Statement (Consolidated)



Particulars (₹ Mn)	Sep FY25	Sep FY26
Cash flow from operating activities		
Profit before tax	1,491	2,478
Adjustment for non-operating items	158	886
Operating profit before working capital changes	1,648	3,364
(Increase)/ decrease in inventories	-1,646	-1,679
(Increase)/decrease in trade receivables	-1,809	-6,029
(Increase)/decrease in payables & other adjustments	-206	2556
Cash generated from operations	-2,013	-1,789
Less: direct taxes paid	-290	-389
Net cash from operating activities	-2,303	-2,178
Cash flow from investing activities	-715	-12,699
Cash flow from financing activities	3,274	14,963
Net increase/ (decrease) in cash & cash equivalent	256	85
Add: Cash and cash equivalents as at 1st April	194	474
Add: Net effect of exchange gain on cash and cash equivalents		
Cash and cash equivalents for period ending	450	559

Profit & Loss Statements (Consolidated)



Particulars (₹ Mn)	FY23	FY24	FY25
Revenue from operations	11,261	18,046	27,218
Raw material cost	7,801	13,299	18,997
Employee expenses	771	1,028	1,781
Other expenses	1,006	1,178	2,333
EBITDA	1,683	2,542	4,107
EBITDA margin (%)	14.9%	14.1%	15.1%
Depreciation and amortization expense	187	251	447
Other income	114	559	1070
Finance cost	349	534	1013
Profit before tax	1,260	2,316	3,716
Total tax expenses	308	483	782
Net profit after tax	952	1,833	2,934
Net profit margin (%)	8.5%	10.2%	10.8%

Balance Sheets (Consolidated)



Particulars (₹ Mn)	FY23	FY24	FY25
Gross Block (tangible assets)	1,451	3,276	6,263
Accumulated Depreciation	549	682	1,218
Net Block (tangible assets)	902	2,594	5,045
Intangible assets	426	620	2,381
Other non-current assets	552	3,571	12,154
Total non-current assets	1,880	6,785	19,580
Inventories	4,132	5,483	8,144
Trade receivables	2,271	3,556	5,746
Cash and cash equivalents	4,860	15,256	10,563
Other current assets	1,045	1,572	2,379
Total current assets	12,308	25,867	26,832
Total Assets	14,187	32,652	46,412
Borrowings	150	112	675
Other non-current liabilities	282	293	474
Total non-current liabilities	432	405	1,149
Short-term borrowings	1,209	2,949	8,080
Trade payables	2,229	3,610	6,829
Other current liabilities	714	803	1,912
Total Current Liabilities	4,152	7,362	16,821
Total Equity & Reserves	9,604	24,885	28,442
Total Equity and Liabilities	14,187	32,652	46,412

Cash Flow Statements (Consolidated)



Particulars (₹ Mn)	FY23	FY24	FY25
Cash flow from operating activities			
Profit before tax	1,260	2,316	3,716
Adjustment for non-operating items	452	401	626
Operating profit before working capital changes	1,713	2,717	4,343
(Increase)/ decrease in inventories	-1868	-1,352	-2,661
(Increase)/decrease in trade receivables	-293	-1,420	-2,190
(Increase)/decrease in payables & other adjustments	535	1,238	4,390
Cash generated from operations	87	1,183	-179
Less: direct taxes paid	-503	-481	-644
Net cash from operating activities	-416	701	-823
Cash flow from investing activities	-4,937	-15,052	-3,547
Cash flow from financing activities	5,543	14,286	4,650
Net increase/ (decrease) in cash & cash equivalent	191	-65	280
Add: Cash and cash equivalents as at 1st April	69	259	194
Add: Net effect of exchange gain on cash and cash equivalents	0	0	0
Cash and cash equivalents as at 31st march	259	194	474



Company Overview

Company Overview



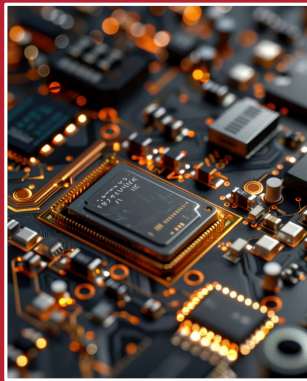
1 – Electronic System & Design Manufacturer; 2- As per Care Edge report; 3 – As of FY25, 22*- HDI PCB is upcoming (OSAT Unit 1/ Golden Line now operational)

Leading integrated Electronics player in India



With backward integration into PCB and vertical integration in OSAT

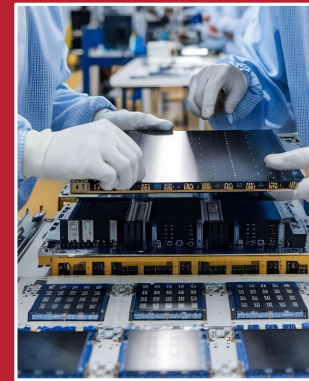
Well Positioned to deliver comprehensive and integrated solutions to customers



Printed Circuit Board



EMS

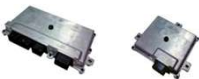


OSAT
(Assembly Testing Packaging)

Better involvement in the larger electronics supply chain, spanning across wafer to end user product

We are fundamentally redefining our position in the ESDM ecosystem. The strategic integration of our core EMS expertise with advanced OSAT and PCB manufacturing capabilities creates an unparalleled competitive moat. This integrated approach grants Kaynes complete, predictive visibility across the full electronics supply chain, enabling us to accelerate time-to-market for clients and strategically advance toward becoming a fully integrated electronics ODM

Diversified product portfolio

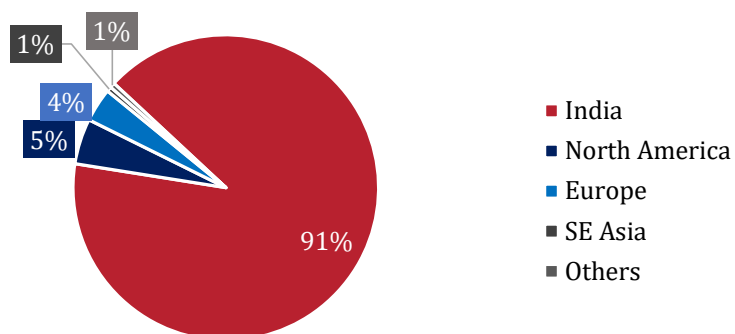
Automotive	Industrial & EV	Railways	Medical	Aerospace, Outerspace & Strategic electronics	IOT/IT, Cons and others
Cluster PCBA  LED Headlamp/Tail Lamp/LED Position Lamp/DRL PCBA  Switches PCBA¹  BCU Master / BCU Slave PCBA 	Engine Control Panel  Street light controller  Smart Energy Meter  Precision Bridge and Strain Gage 	UM71 - Receiver  ETCS cubicle  SDTC cubicle  SDTC Card File 	Endoscopy cart & ICP sensor module  X-ray & Dental X-ray machine  Controller Units  Protein & clinical chemistry analyzers 	HH Sonar  Mission Critical Products²  ESAF  ATE & LRU Cable Assemblies 	Bar Code Scanner & RFID gateway  PLC & Asset Condition Monitoring gateway  Sensors  Industrial HMI Reader & Industrial Tablet 

1 - Headlamp level switch / Steering control switch/ Windowlift Motor/ Rocker Switch PCBA | 2 - Kaynes has been a valuable industry partner for soft landing of Chandrayaan-3 & launch of Aditya-L1 missions

Revenue mix- Pie chart change

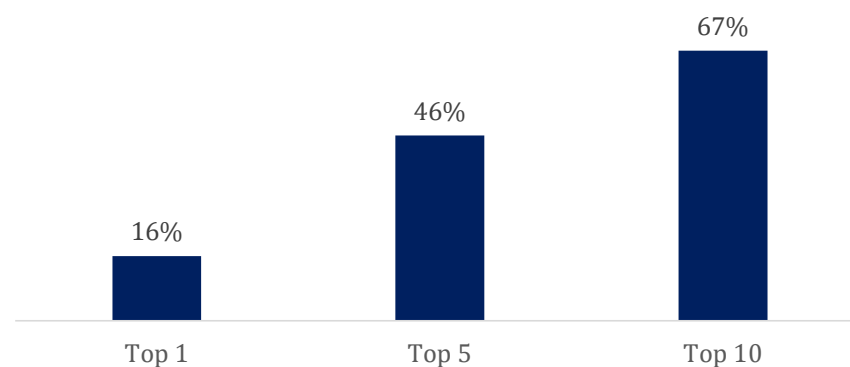
FY25

Revenue across geographies



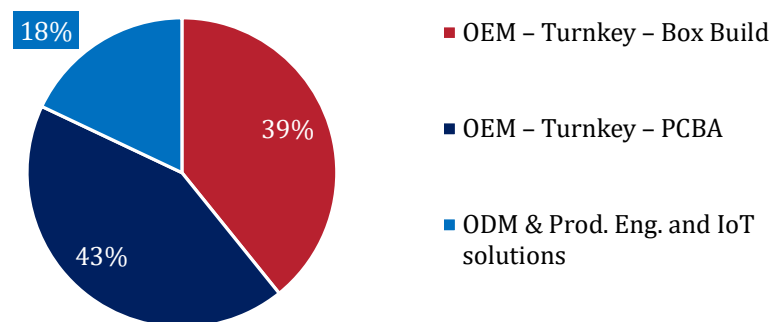
Low customer concentration

FY25



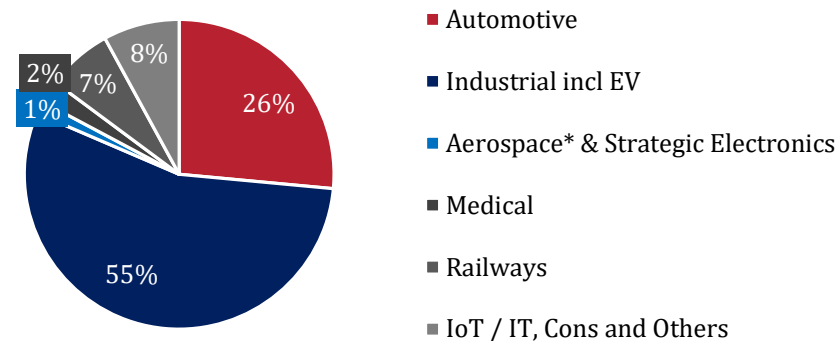
FY25

Revenue across segments



Revenue across verticals

FY25



Note: Aerospace* segment also includes Outer-Space

Marquee customer base

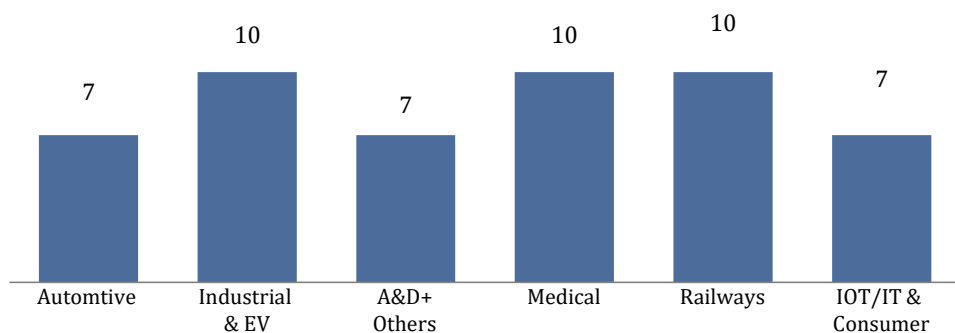


Industry	Industrial	Railways	Automotive	Medical	Aerospace+ Others ¹	IoT / IT and others
Key Customers	Leading global mfg of electronic instruments and electromechanical devices	SIEMENS FRAUSCHER HITACHI		AGAPPE BeatO	TONBO imaging CANYON aerconnect	सी डैक CDAC

Long standing relationship with clients**

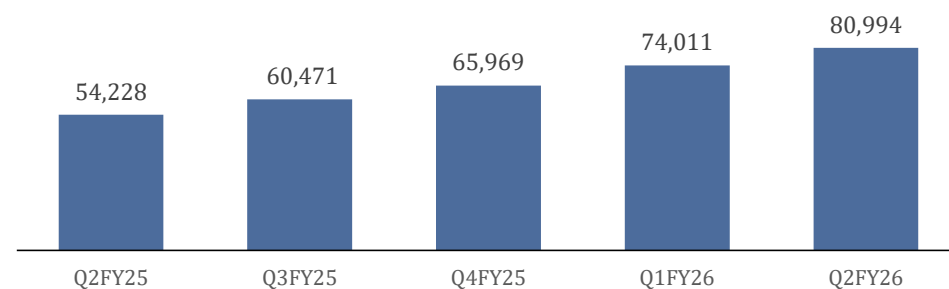
INR Mn

Average business period relationship of top 10 customers in each vertical²



Strong order book

INR Mn



¹ – Aerospace, Outer space and strategic electronics; ² - Average period of business relationship is determined based on the length of relationship of top 10 customers in each vertical. Relationship with clients** with customer as of FY25

R&D & Engineering, Certifications and Supply Chain



Research and Development

Focused on development of new products and improvement existing products

Dedicated research facility at Mysore, Bangaluru & Ahmedabad with a 200+ member R&D & Engineering Team¹

Operations complying with global standards with 13 global accreditations –most for an ESDM company in India^{1,3}

Facilities approved by global certifications Agencies E.g. Underwriters Laboratories, CSA2, TUV Rhineland



Certifications

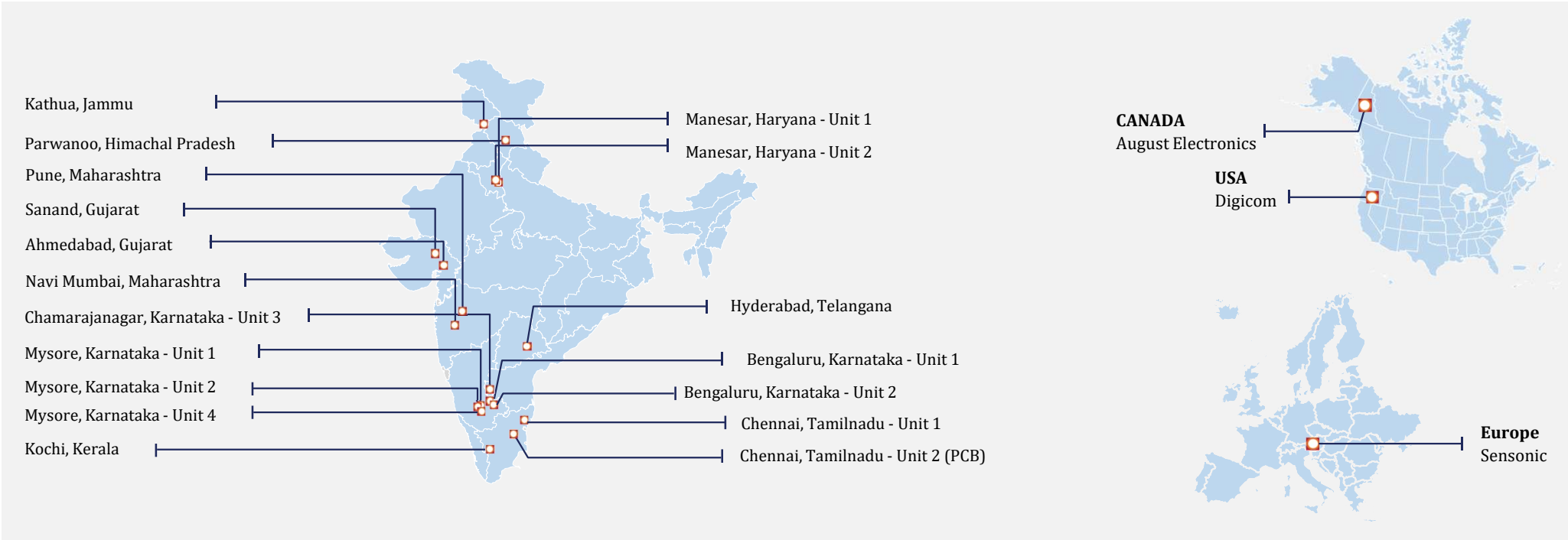


Supply chain

Long term relationship with suppliers leading to better credit terms

Suppliers with multiple sources for a single component with specialized dealers for niche verticals

Capacity for Manufacturing at Local & Global Scale Augmented by Technical Capabilities



25+ SMT Lines	70 THD Lines	26 Cable Harness Lines	15 plastic molding machines	10K class clean room
Commissioning of the Pilot Line/Unit 1 for OSAT	Most manufacturing at low-cost locations	Dedicated humidity-controlled stores	Fungible infrastructure	2 exclusive RoHS compliant lines for green manufacturing

Kaynes Expansion – Chamaraajanagar



- Built-up area of ~ 350K sq ft
- Well supported by ancillary facilities of existing units / expansion plans
- Phase-I: Alpha & Beta Ready (~100K sq ft)
- Phase-II:
 - Gamma ready for operations i.e. ~240,000 Sq feet
 - Clean Room of Class 10K
 - Wire Bonding
 - Box Build
 - Aerospace vertical

Kaynes Expansion – Hyderabad



- Location: Kongara Kalan (Near Hyderabad Airport)
- Total Plant Area: 70K SFT
- SMT Lines -1 Number
- Plastic Injection Machines- 29 NOS (80 -350 TON)



Backward integration – OSAT & HDI PCB subsidiaries



- Built-up area Unit 1 – Plant 1 (Golden Line) area of ~ 3,282 Sq ft
- Built up area Unit 1- Plant 2 area of ~ 241K Sq ft
- Phase 2 Expansion- 236K Sq ft
- Key Packages include:
 - Legacy packages: QFN, TO
 - Semi- Advance Packages: BGA, Flip Chip BGA
 - Advance Packages: 2D, 2.5D, 3 D along with Co-Package Optics
- Key Areas of Usage:
 - Power electronics for Automotive, Healthcare, Industrial
 - Consumer goods
 - Wireless devices & IoT

Kaynes Circuits – Chennai



- 1. About 5 Million SQ MT of PCB Manufacturing Capacity in India
- 2. Multi Layer PCB both Rigid and Rigid Flex (High Layer Count Printed Circuit Boards, of up to 74 layers).
- 3. HDI PCB (High Density Interconnect Boards)
- 4. Flexible PCB (up to 16 layers.)
- Key Areas of Usage:
 - Telecom
 - Medical
 - Auto- EV
 - Strategic sectors
 - Smart Phones

Key Investments & Acquisitions

Key Investments & Acquisitions Driving Technological & Global Reach



August Electronics Inc.

- Overview: Canada-based EMS provider catering to high-reliability sectors such as energy, medical, telecom, and industrial
- Core Capabilities: Consumer electronics manufacturing, Medical device manufacturing, PCB assembly, Box build integration, Repairs and refurbishment & Design for manufacturing
- Strategic Relevance: Strengthens North American manufacturing footprint and diversified customer base



Canada

Tranzmeo IT Solutions Pvt Ltd

- Overview: Focused on AI, machine learning, and fibre optic sensing technologies
- Core Capabilities: Anomaly and intrusion detection, remote monitoring, and intelligent automation
- Strategic Relevance: Adds AI-driven analytics and smart sensing solutions, aligning with next-gen Industry 4.0 offerings



Canada

Sensonic GmbH

- Overview: Converts fibre-optic cables into smart sensing networks for rail monitoring
- Core Capabilities: Uses AI-driven acoustic sensing to detect track issues & security threats
- Strategic Relevance: Expands Kaynes' footprint in smart rail-tech and IoT solutions

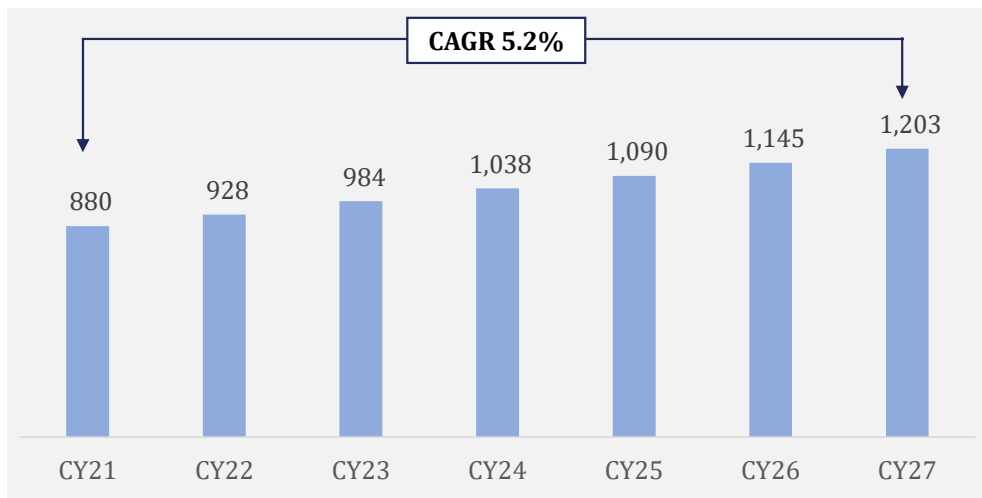


Austria

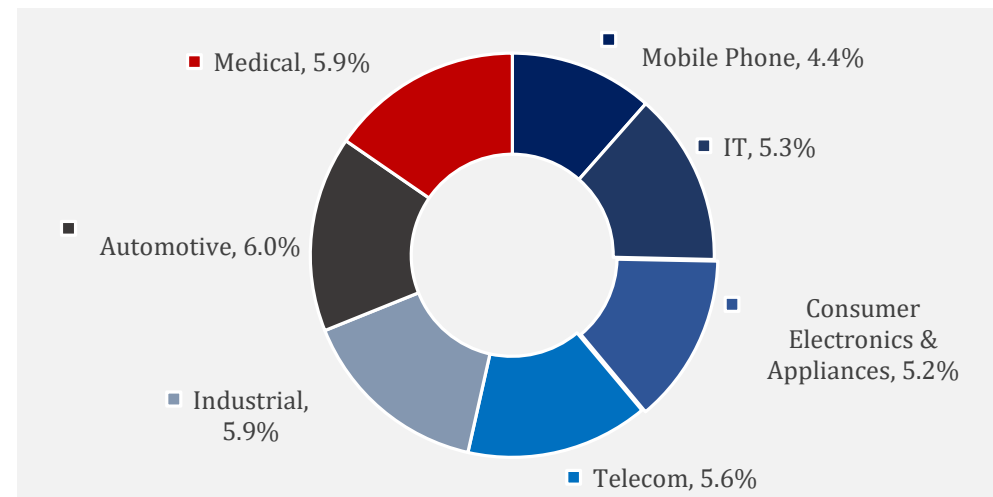
Industry Overview

Industry Update (ESDM)

Global ESDM Market Size (US \$ BN)



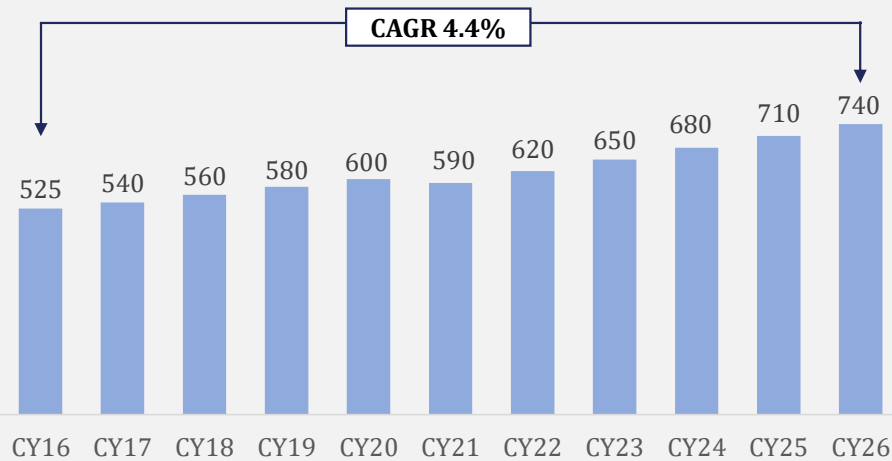
Global ESDM Segment CAGR from CY 2023 to CY 2027 (E)



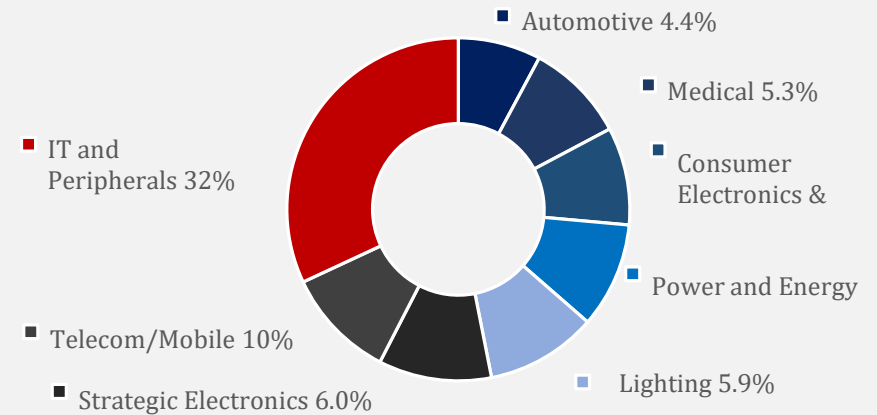
- The global Electronic System Design and Manufacturing (ESDM) industry is undergoing a significant shift from traditional OEM-led production to integrated system-level partnerships.
- Companies operating within the ESDM value chain are increasingly providing end-to-end solutions across the product lifecycle—encompassing design, prototyping, assembly, testing, and post-sales support.
- Robotic manufacturing, smart factories, and real-time data analytics are transforming productivity and efficiency in global ESDM
- Growth in decentralized computing architectures necessitates the development of high-performance but energy-efficient hardware for real-time processing at network edges

Industry Update (PCBA)

Global PCBA Industry Market Size (US \$ BN)



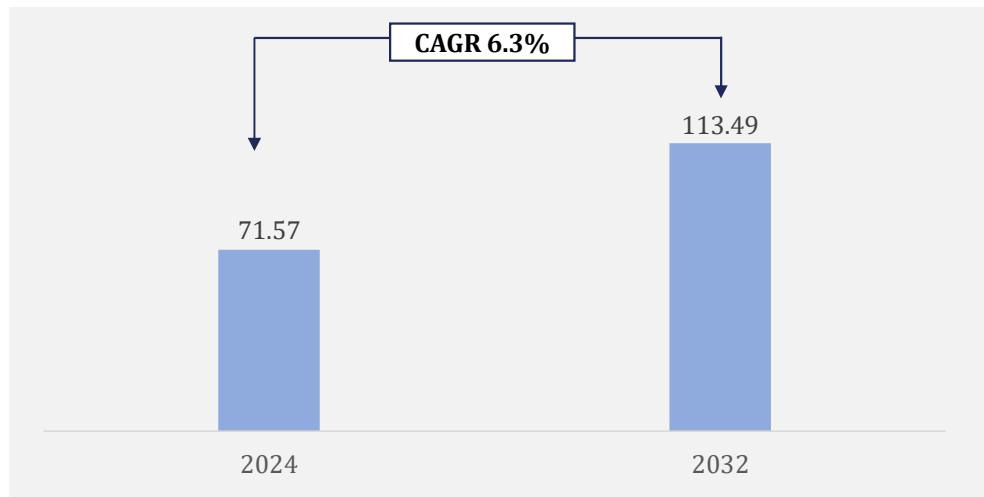
Global PCBA Market Share by Industry



- The significant growth in PCBA underscores the industry's widespread relevance across various end-user domains such as telecommunications, IT hardware, automotive, consumer electronics, medical equipment, and other strategic sectors.
- PCBAs cater to both large-scale consumer products and specialized, low-volume applications that require high precision and reliability. As the central hub for integrating electronic components, the PCBA sector serves as a cornerstone of the global electronics manufacturing landscape.
- With devices becoming increasingly compact, intelligent, and interconnected, the demands on PCBA complexity and performance have grown substantially. This has amplified their role not just in assembling final products, but also in driving innovation, ensuring quality, and enhancing functional efficiency across a broad range of technologies.

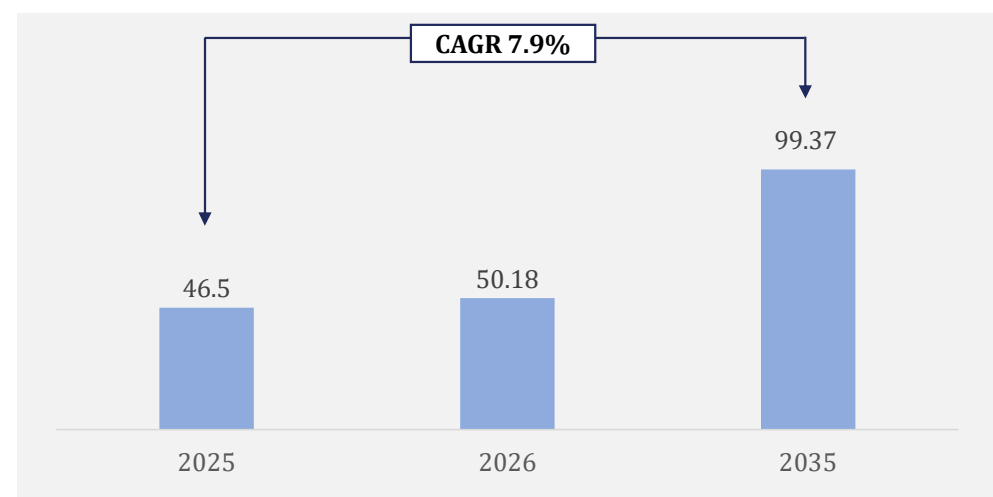
Source: Annual Report FY25

Global PCB Industry Market Size (US \$ bn)¹



- Demand driven by key factors such as growth in consumer electronics, industrial automation, and applications across automotive, telecommunication, healthcare, and energy.
- After COVID-19 disruptions, the market rebounded due to increased sales and prices, while advances in display technologies and flexible PCBs fuel long-term growth.
- India's PCB market is booming, projected to grow from USD 6.3 billion in 2024 to USD 24.7 billion by 2033 at a blistering CAGR of 15.6%—far outpacing global averages.
- This growth is fueled by government incentives (PLI, Make in India), localization of electronics supply chains, and telecom (5G) infrastructure, and a surge in advanced multilayer and flexible PCB technologies.

Global OSAT Industry Market Size (US \$ bn)



- While the Asia-Pacific region dominates with over 70% market share due to established supply chains, North America is witnessing growth through reshoring initiatives.
- The Indian OSAT market is expected to grow at 8–15% CAGR (using different data sets), benefiting from booming electronics consumption, strategic partnerships with global players, and an increasing focus on advanced packaging technologies such as System-in-Package (SiP), 2.5D/3D, and fan-out panel-level packaging

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THANK YOU